

HV regulation board for the forward endcap - Status -

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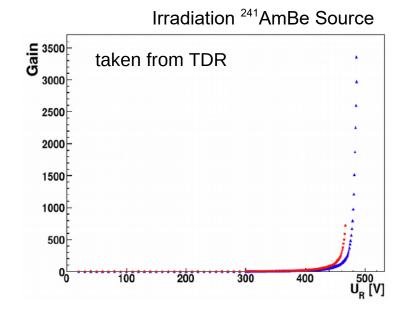


Introduction



Motivation

- Reach gain spread of max. 1%
- More freedom in matching procedure (less strict), G(U) very steep @200
- Be able to compensate different gain drifts of APDs due to radiation damage on long term



Original idea voltage distribution

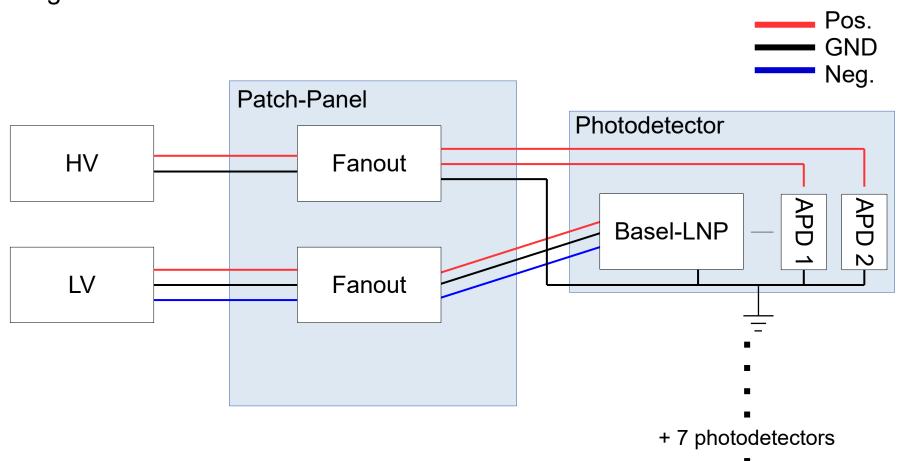
Due to very limited cross section for HV cables

One HV is fed to 8 APDs

Power distribution concept



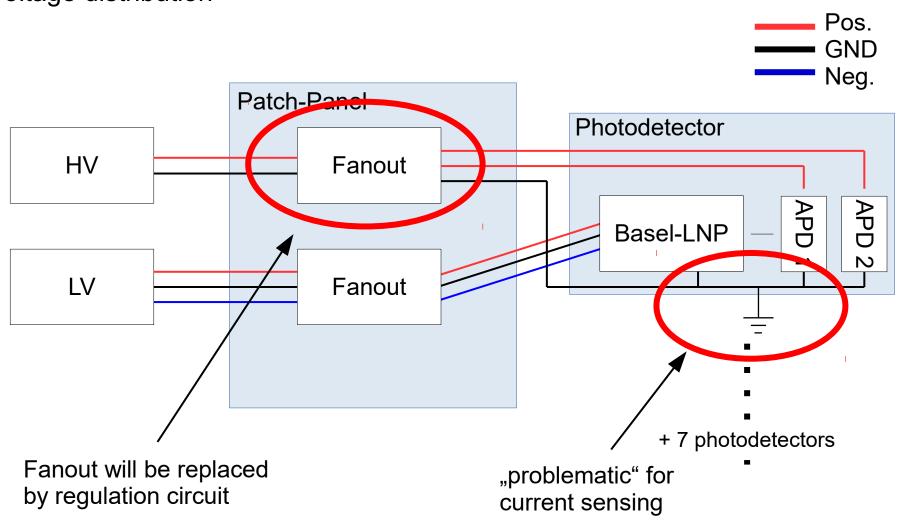
Voltage distribution



Power distribution concept



Voltage distribution



Starting point



Reuse HV regulation circuit from the Crystal Barrel Exp.@ELSA (also used in the barrel part)

- Regulation range 10Bit (100-500V)
- Temp. compensation
- I²C controlled

Special adaption for forward endcap

- 8%/V @ gain 200 → ~ 0,1V Voltage resolution
- Resonably regulation span (~25-40V)
- Accurate HV voltage measurement
- (Current measurement)

Mechanics – space constraints



30 (mountingplate

Extrem dense situation behind the backplate

All cables have to fit in a depth of 3.3cm

 Patch panel is interconnection of alveole to "outside" cables

Add piggyback board

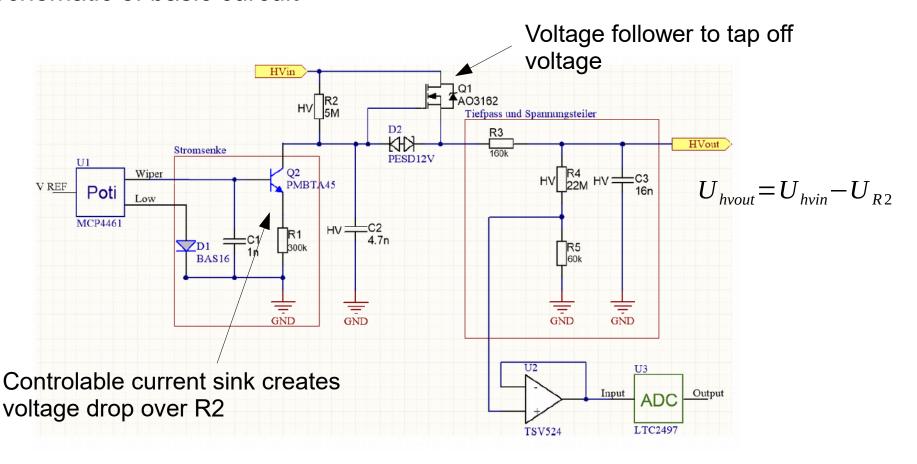
- As close as possible to existing patch panel
- Adds space for components of about 73 cm²

Piggyback board helps in mounting procedure

Voltage regulation



Schematic of basic curcuit

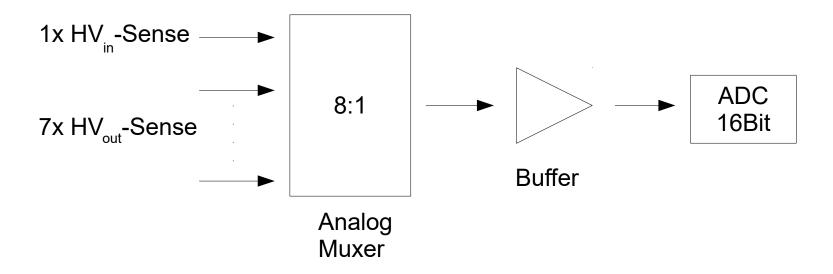


Whole basic circuit is needed 32x for 16er and 16x for 8er alveole

Voltage regulation



Instead of 32 OP-amps and 2 ADCs, sense voltages switched by muxer



Pros

- Monitoring of input voltage
- Recalibration of ADC channels possible after mounting

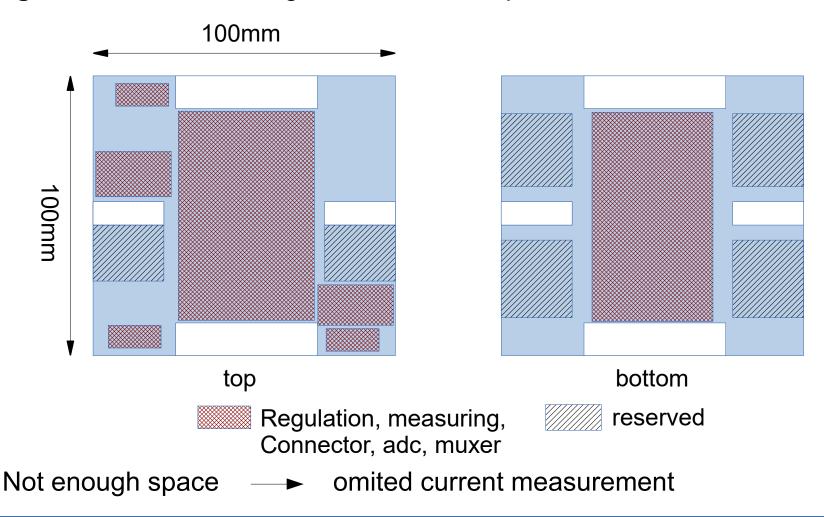
Cons

Only 4/5 channels can be converted at once

Space constraints



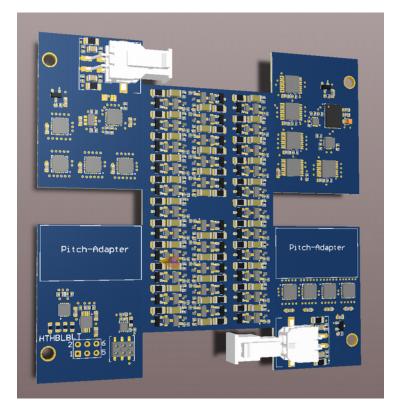
Almost all space used by regulation, measurement and connectors **high side** current sensing needs more components



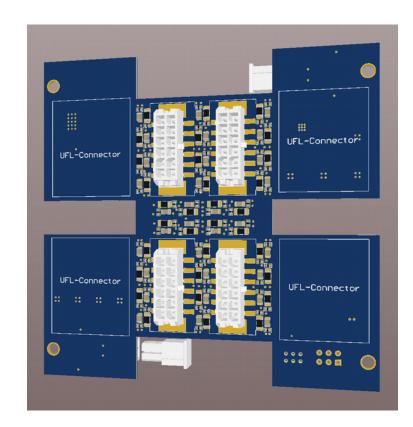
Board layout



Current design

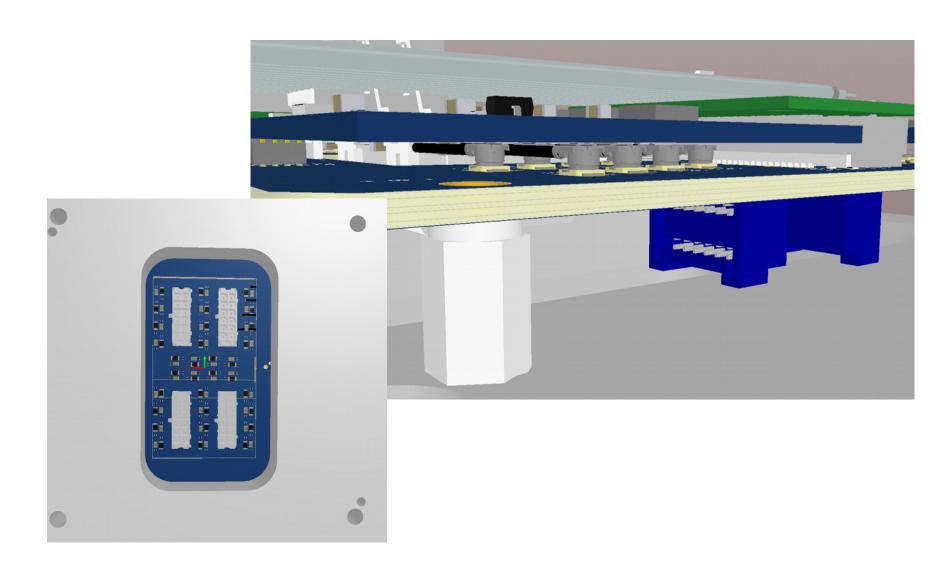


Top side Bottom side



Board layout





Cable "problem"



264 patch panel boards (16er/8er size) on each, one HV board

No room for 264 cables from available cross section.

► In maximum ~32 cables possible

I²C

- 2 pairs via differential I²C (Data, CLK)
- chainable

SPI

- 4 single ended lines (SS, MOSI, MISO, CLK)
- chainable

To reduce cable count boards needs to be cascaded

16 boards → ~ 16 cables

8 boards \rightarrow ~ 32 cables

Dangerous:

If data- or clock-lines get stuck, one loses control of connected boards

Test boards



Due to different chip selection (dig. Poti, ADC) from original design, tests are needed

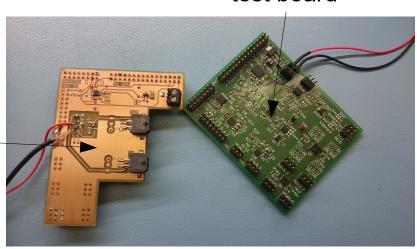
Test parameter of chips under different conditions

- Radiation
 - Test chips (I²C, ADC, Poti,...) up to a radiation dose of 500Gy
 - 4 runs of 125 Gy
- Temperature-cycles / dependence

Longterm stability of voltage

1-Channel prototype

I2C components test board



Radiation tests



Test of digital potentiometer by measuring Resistance by 6,5digit multimeter



MCP444X/446X

7/8-Bit Quad I²C Digital POT with Nonvolatile Memory

Comparing the voltage divider factor for different radiation doses:

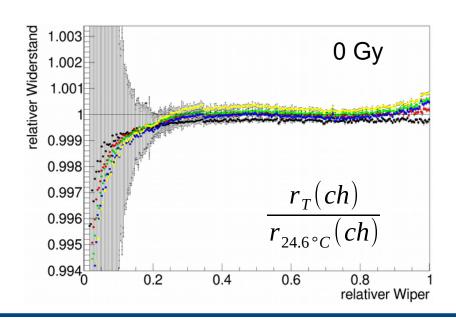
$$r_{T}(ch) = \frac{R_{T}(ch)}{R_{T}^{max}}$$

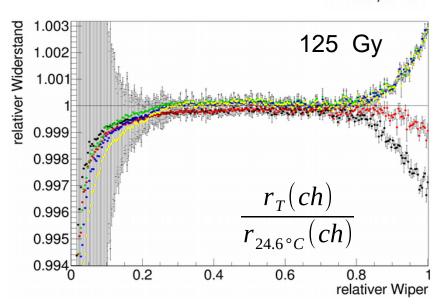


■ 0,2°C ■ -10,2°C

-20,2°C

-29,8°C





Radiation tests

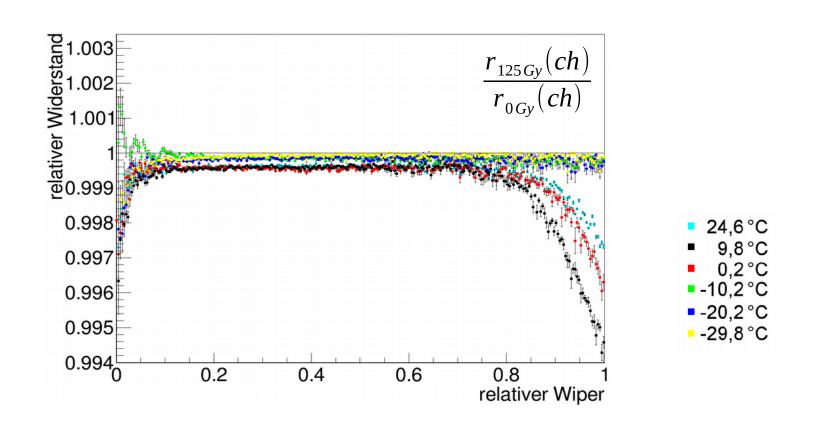


Test of digital potentiometer by measuring Resistance by 6,5digit multimeter



MCP444X/446X

7/8-Bit Quad I²C Digital POT with Nonvolatile Memory



Radiation tests

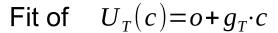


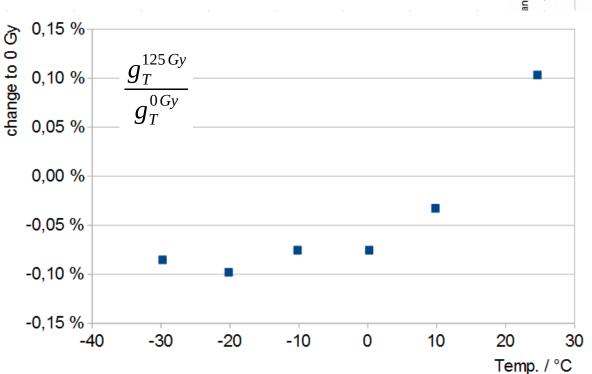
Stimulate ADC input with external voltage source (0-1.5V)

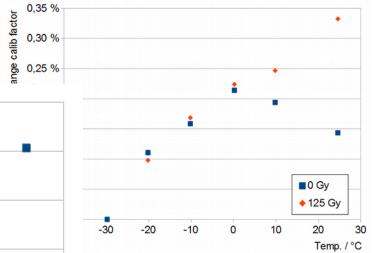


0,35 %

LTC2497 16-Bit 8-/16-Channel

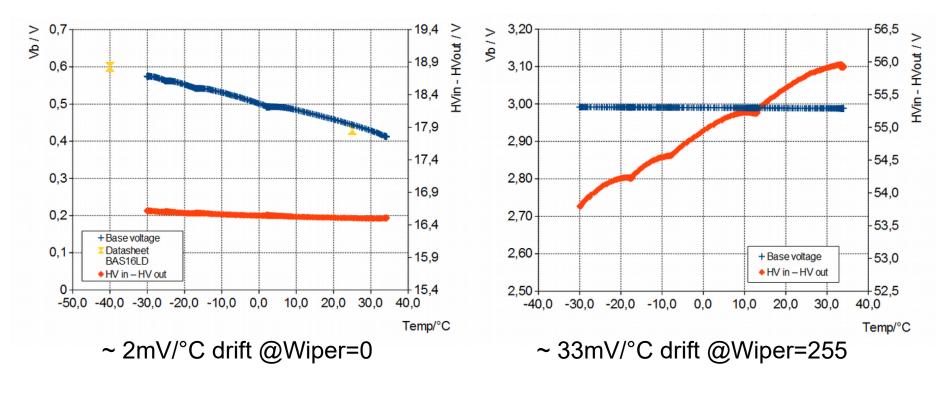








High voltage output - temperature dependence



- Current design compensates temp. dependence only partly
- If temp. is stable below 0.5°C, temp. dependence will be max. 16mV

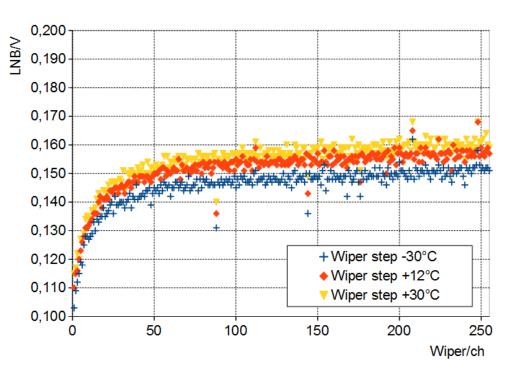
Ref. Voltage 3V

~ 60µV/°C temp. dependence (datasheet max. 80ppm/°C)



High voltage output - step size (LNB)

Digital potentiometer (MCP446X) with 8Bit resolution



Alternative to MCP 446x:

Serial adapter chip (integrated 10bit DAC) see talk H. Flemming can increase the range by factor of 3 \longrightarrow 40V to 120V or the resolution by factor 3 \longrightarrow 150mV to 50mV



High voltage output - long term stability

Measurement at a fixed temperature in comparison to a 6,5digit multimeter (Keysight 34465A)

HV_{in}, HV_{out} 6,5digit DMM

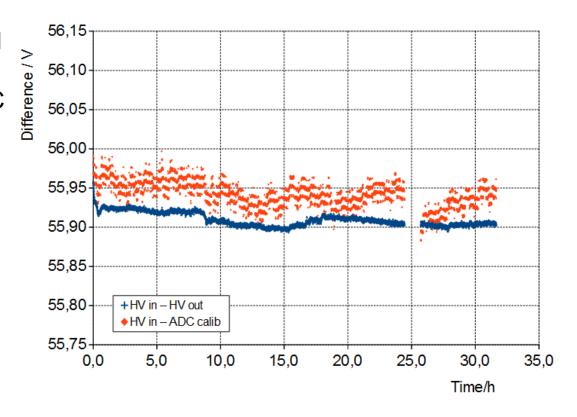
ADC calib onboard ADC

To be independent of Hvin fluctuations use difference

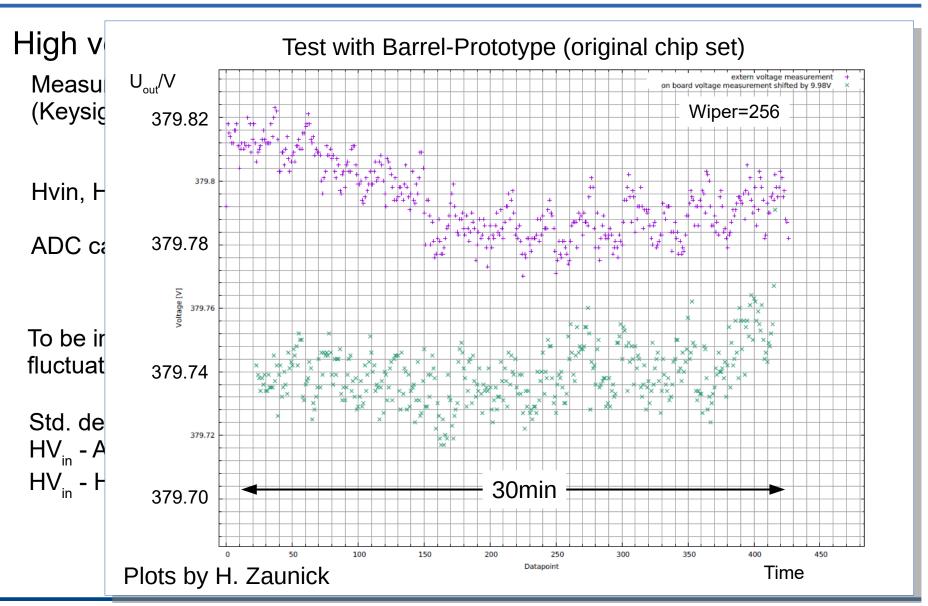
Std. deviation:

 HV_{in} - ADC $\rightarrow 25mV$

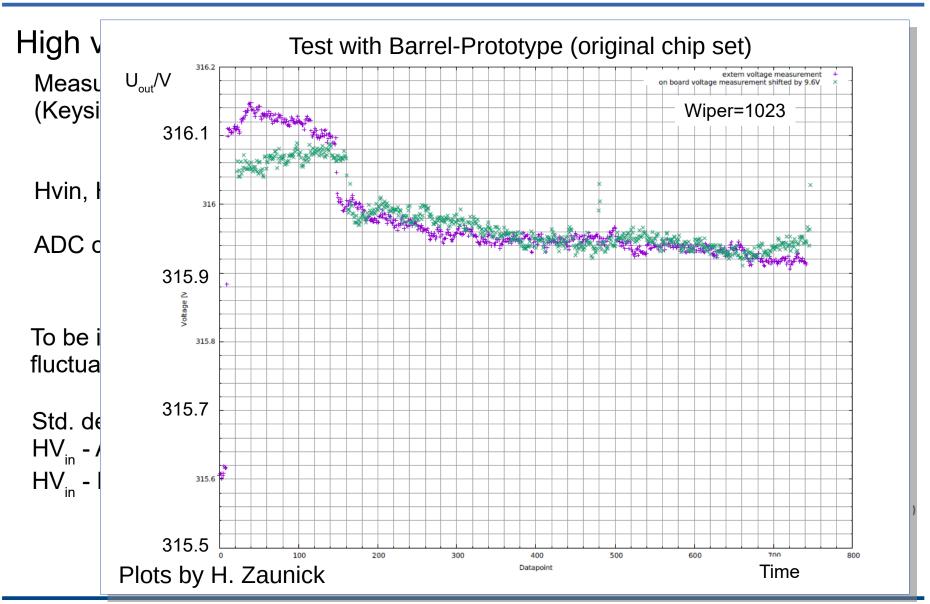
 $HV_{in} - HV_{out} \rightarrow 10 mV$





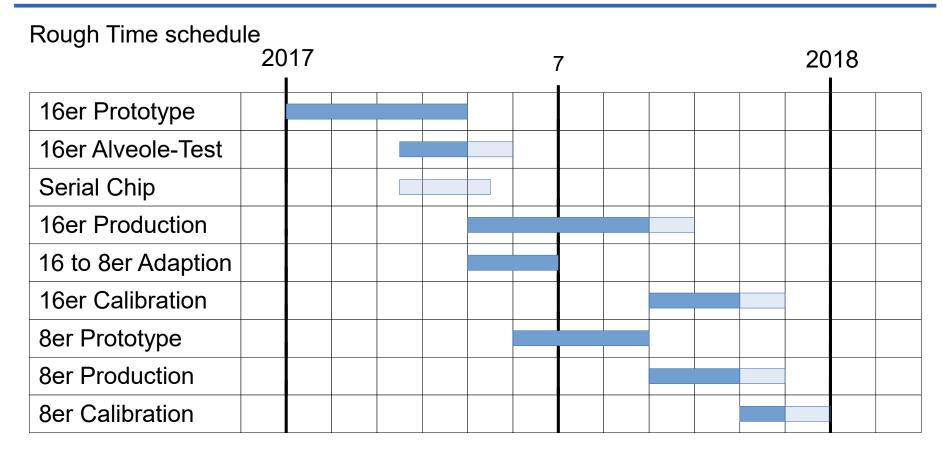






Next steps



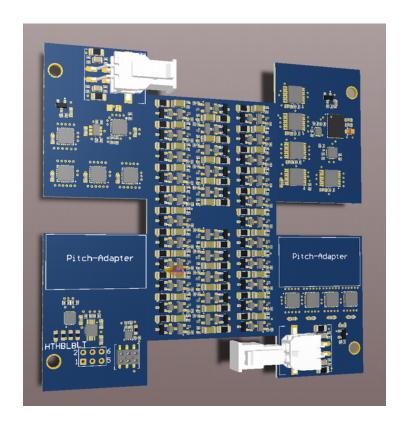


Near future steps

- Finalize layout 16er
- Build prototype
- Test 16er with APD Alveole

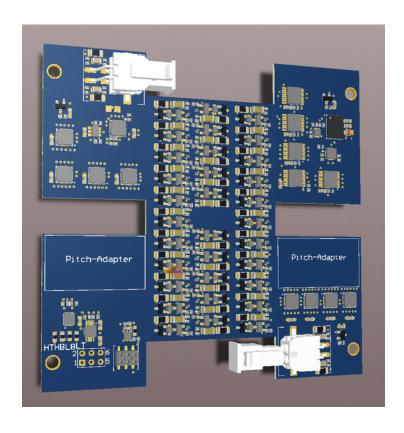


Thank you for your attention





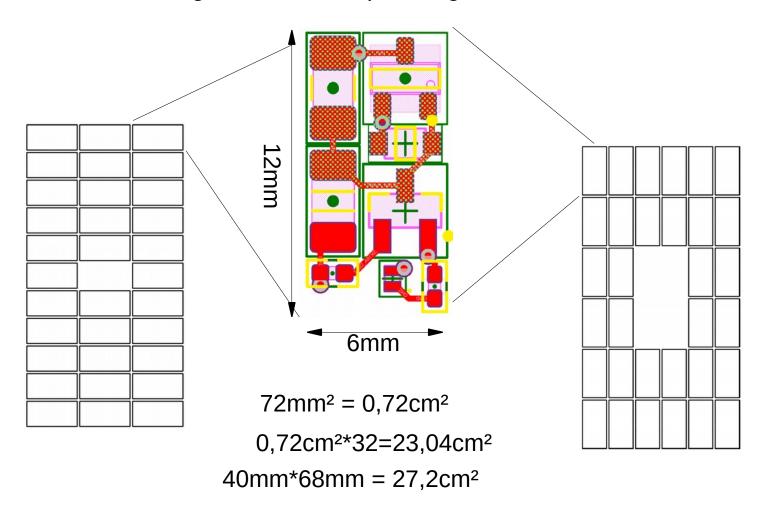
Backup slides



Space consumption



Current sink and voltage follower on top, Voltage divider near connector on bottom



Basic principle



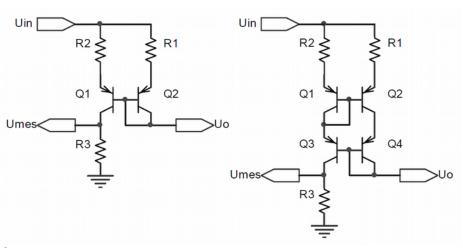
Current measurement circuit

Grounding concept in photodetector needs a highside current measuring circuit

Wilson Current Mirrors

mirrors current from the high side to a low side, where measuring can be

done via a shunt resistor



Problems

Find FETs that can with stand 500V on \mathbf{U}_{DS}

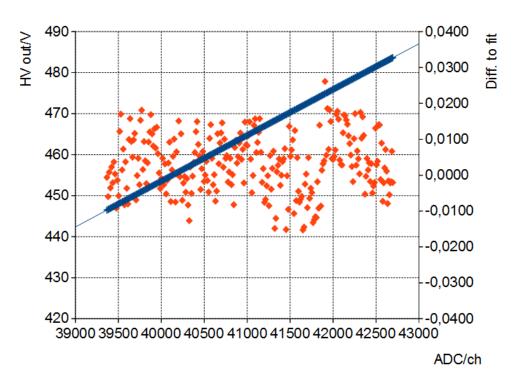
Needs much space (+additional parts to convert digital)

Current sensing omited



High voltage output - voltage measurement

Output measured by 6,5digit DMM and sweep of potentiometer from 0 to 255. 3mV over Calibration

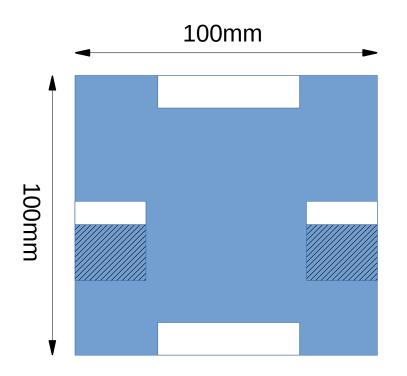


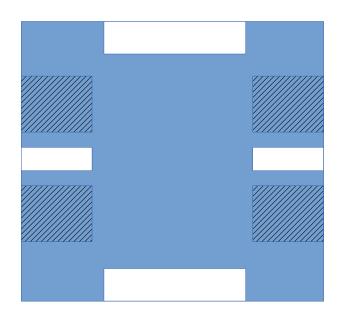
Maximal variation from a linear calibration ~+/-20mV

Space constraints



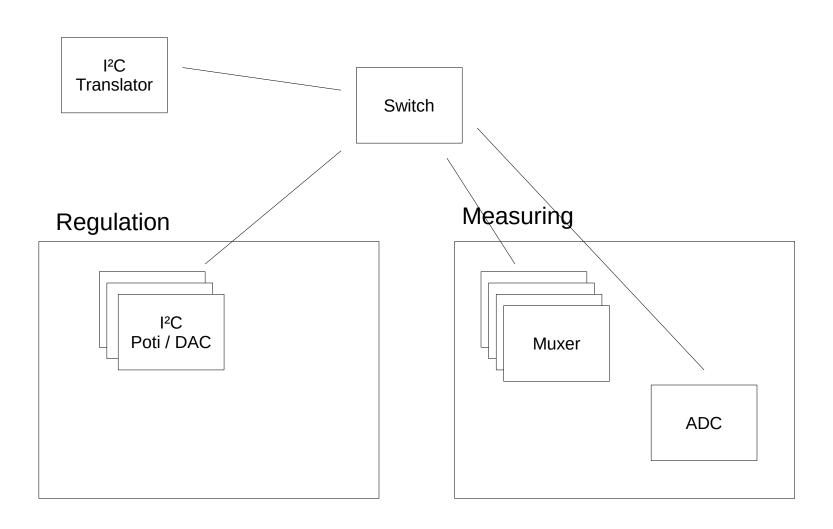
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I²C structure





I²C structure



I²C standard allows 7 or 10 bit adr.

- 7 bit commonly used, 10 bit not on every chip
- 128 16 = 112 adr.
- I²C switches, adr. translation
- Diff. I²C

Chip selection for current sink control

- Microchip MCP4464, 8Bit dig. Poti
- GSI chip, 10Bit DAC